



## Material Content Data Sheet



| <b>Sales Product Name</b> |                    | BTS3046SDL     |                    | <b>Issued</b>  |                  | 29. August 2013 |                    |           |
|---------------------------|--------------------|----------------|--------------------|----------------|------------------|-----------------|--------------------|-----------|
| <b>MA#</b>                |                    | MA001111552    |                    |                |                  |                 |                    |           |
| <b>Package</b>            |                    | PG-TO252-3-11  |                    | <b>Weight*</b> |                  | 391.81 mg       |                    |           |
| Construction Element      | Material Group     | Substances     | CAS# if applicable | Weight [mg]    | Average Mass [%] | Sum [%]         | Average Mass [ppm] | Sum [ppm] |
| chip                      | inorganic material | silicon        | 7440-21-3          | 3.370          | 0.86             | 0.86            | 8600               | 8600      |
| leadframe                 | non noble metal    | iron           | 7439-89-6          | 0.140          | 0.04             |                 | 357                |           |
|                           | inorganic material | phosphorus     | 7723-14-0          | 0.042          | 0.01             |                 | 107                |           |
|                           | non noble metal    | copper         | 7440-50-8          | 139.706        | 35.66            | 35.71           | 356566             | 357030    |
| wire                      | non noble metal    | aluminium      | 7429-90-5          | 1.745          | 0.45             | 0.45            | 4453               | 4453      |
| encapsulation             | organic material   | carbon black   | 1333-86-4          | 1.454          | 0.37             |                 | 3710               |           |
|                           | plastics           | epoxy resin    | -                  | 25.436         | 6.49             |                 | 64920              |           |
|                           | inorganic material | silicondioxide | 60676-86-0         | 118.460        | 30.23            | 37.09           | 302342             | 370972    |
| leadfinish                | non noble metal    | tin            | 7440-31-5          | 3.740          | 0.95             | 0.95            | 9546               | 9546      |
| plating                   | non noble metal    | nickel         | 7440-02-0          | 0.091          | 0.02             |                 | 232                |           |
|                           | inorganic material | phosphorus     | 7723-14-0          | 0.000          | 0.00             | 0.02            | 1                  | 233       |
| solder                    | noble metal        | silver         | 7440-22-4          | 0.075          | 0.02             |                 | 192                |           |
|                           | non noble metal    | tin            | 7440-31-5          | 0.060          | 0.02             |                 | 154                |           |
|                           | non noble metal    | lead           | 7439-92-1          | 2.879          | 0.73             | 0.77            | 7348               | 7694      |
| heatspreader              | non noble metal    | iron           | 7439-89-6          | 0.095          | 0.02             |                 | 241                |           |
|                           | inorganic material | phosphorus     | 7723-14-0          | 0.028          | 0.01             |                 | 72                 |           |
|                           | non noble metal    | copper         | 7440-50-8          | 94.488         | 24.12            | 24.15           | 241159             | 241472    |
| *deviation                | < 10%              |                |                    |                | Sum in total:    | 100.00          |                    | 1000000   |

### Important Remarks:

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